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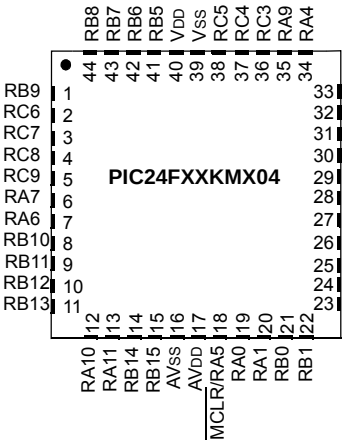
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	18
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08km101-i-so

Pin Diagrams (Continued)

44-Pin TQFP/QFN(1)



Pin	Pin Features	
	PIC24FXXKMX04	PIC24FVXXKMX04
1	AN21/SDA1/T1CK/U1RTS/U1BCLK/IC2/ /CLC1O/CTED4/CN21/RB9	
2	U1RX/ /CN18/RC6	
3	U1TX/ /CN17/RC7	
4	/CN20/RC8	
5	IC4/OC2F/CTED7/CN19/RC9	
6	IC1/ / /CTED3/CN9/RA7	
7	/OC1A/CTED1/INT2/CN8/RA6	VCAP or VDDCORE
8	PGED2/SDI1/OC1C/CTED11/CN16/RB10	
9	PGEC2/SCK1/OC2A/CTED9/CN15/RB11	
10	/AN12/HLVDIN/ /CTED2/ CN14/RB12	/AN12/HLVDIN/ /CTED2/INT2/ CN14/RB12
11	/ /AN11/SDO1/OC1D/CTPLS/CN13/RB13	
12	/ /CN35/RA10	
13	/ /CTED8/CN36/RA11	
14	/CVREF/ / /AN10/ / /C1OUT/OCFA/CTED5/INT1/CN12/ RB14	
15	/ /AN9/ /REFO/SS1/TCKIA/CTED6/CN11/RB15	
16	AVSS	
17	AVDD	
18	MCLR/VPP/RA5	
19	CVREF+/VREF+/ /AN0/ /CN2/ RA0	CVREF+/VREF+/ /AN0/ / CTED1/CN2/RA0
20	CVREF-/VREF-/AN1/CN3/RA1	
21	PGED1/AN2/CTCMP/ULPWU/C1IND/ / / /CN4/RB0	
22	PGEC1/ / /AN3/C1INC/ / /CTED12/CN5//RB1	
23	/ /AN4/C1INB/ / /TCKIB/CTED13/CN6/RB2	
24	/AN5/C1INA/ / /CN7/RB3	
25	AN6/CN32/RC0	
26	AN7/CN31/RC1	
27	AN8/CN10/RC2	
28	VDD	
29	VSS	
30	OSCI/CLKI/AN13/CN30/RA2	
31	OSCO/CLKO/AN14/CN29/RA3	
32	OCFB/CN33/RA8	
33	SOSCI/AN15/ / /CN1/RB4	
34	SOSCO/SCLKI/AN16/PWRLCLK/ /CN0/RA4	
35	/CN34/RA9	
36	/CN28/RC3	
37	/CN25/RC4	
38	/CN26/RC5	
39	VSS	
40	VDD	
41	PGED3/AN17/ASDA1/OC1E/CLCINA/CN27/RB5	
42	PGEC3/AN18/ASCL1/OC1F/CLCINB/CN24/RB6	
43	AN19/INT0/CN23/RB7	AN19/ /OC1A/INT0/CN23/RB7
44	AN20/SCL1/U1CTS/C3OUT/OC1B/CTED10/CN22/RB8	

Legend: Values in indicate pin function differences between PIC24F(V)XXKM202 and PIC24F(V)XXKM102 devices.

Note 1: Exposed pad on underside of device is connected to VSS.

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TABLE 1-5: PIC24FV16KM204 FAMILY PINOUT DESCRIPTION (CONTINUED)

Function	F					FV					I/O	Buffer	Description
	Pin Number					Pin Number							
	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN			
CN13	16	24	21	11	12	16	24	21	11	12	I	ST	Interrupt-on-Change Inputs
CN14	15	23	20	10	11	15	23	20	10	11	I	ST	Interrupt-on-Change Inputs
CN15	—	22	19	9	10	—	22	19	9	10	I	ST	Interrupt-on-Change Inputs
CN16	—	21	18	8	9	—	21	18	8	9	I	ST	Interrupt-on-Change Inputs
CN17	—	—	—	3	3	—	—	—	3	3	I	ST	Interrupt-on-Change Inputs
CN18	—	—	—	2	2	—	—	—	2	2	I	ST	Interrupt-on-Change Inputs
CN19	—	—	—	5	5	—	—	—	5	5	I	ST	Interrupt-on-Change Inputs
CN20	—	—	—	4	4	—	—	—	4	4	I	ST	Interrupt-on-Change Inputs
CN21	13	18	15	1	1	13	18	15	1	1	I	ST	Interrupt-on-Change Inputs
CN22	12	17	14	44	48	12	17	14	44	48	I	ST	Interrupt-on-Change Inputs
CN23	11	16	13	43	47	11	16	13	43	47	I	ST	Interrupt-on-Change Inputs
CN24	—	15	12	42	46	—	15	12	42	46	I	ST	Interrupt-on-Change Inputs
CN25	—	—	—	37	40	—	—	—	37	40	I	ST	Interrupt-on-Change Inputs
CN26	—	—	—	38	41	—	—	—	38	41	I	ST	Interrupt-on-Change Inputs
CN27	—	14	11	41	45	—	14	11	41	45	I	ST	Interrupt-on-Change Inputs
CN28	—	—	—	36	39	—	—	—	36	39	I	ST	Interrupt-on-Change Inputs
CN29	8	10	7	31	34	8	10	7	31	34	I	ST	Interrupt-on-Change Inputs
CN30	7	9	6	30	33	7	9	6	30	33	I	ST	Interrupt-on-Change Inputs
CN31	—	—	—	26	28	—	—	—	26	28	I	ST	Interrupt-on-Change Inputs
CN32	—	—	—	25	27	—	—	—	25	27	I	ST	Interrupt-on-Change Inputs
CN33	—	—	—	32	35	—	—	—	32	35	I	ST	Interrupt-on-Change Inputs
CN34	—	—	—	35	38	—	—	—	35	38	I	ST	Interrupt-on-Change Inputs
CN35	—	—	—	12	13	—	—	—	12	13	I	ST	Interrupt-on-Change Inputs
CN36	—	—	—	13	14	—	—	—	13	14	I	ST	Interrupt-on-Change Inputs
CTCMP	4	4	1	21	23	4	4	1	21	23	I	ANA	CTMU Comparator Input

Legend: ANA = Analog level input/output, ST = Schmitt Trigger input buffer, I^2C™ = I^2C/SMBus input buffer

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TABLE 1-5: PIC24FV16KM204 FAMILY PINOUT DESCRIPTION (CONTINUED)

Function	F					FV					I/O	Buffer	Description
	Pin Number					Pin Number							
	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN	20-Pin PDIP/ SSOP/ SOIC	28-Pin PDIP/ SSOP/ SOIC	28-Pin QFN	44-Pin QFN/ TQFP	48-Pin UQFN			
$\overline{MCLR}$	1	1	26	18	19	1	1	26	18	19	I	ST	Master Clear (Device Reset) Input (active-low)
OA1INA	—	5	2	22	24	—	5	2	22	24	I	ANA	Op Amp 1 Input A
OA1INB	—	6	3	23	25	—	6	3	23	25	I	ANA	Op Amp 1 Input B
OA1INC	—	24	21	11	12	—	24	21	11	12	I	ANA	Op Amp 1 Input C
OA1IND	—	25	22	14	15	—	25	22	14	15	I	ANA	Op Amp 1 Input D
OA1OUT	—	7	4	24	26	—	7	4	24	26	O	ANA	Op Amp 1 Analog Output
OA2INA	—	5	2	22	24	—	5	2	22	24	I	ANA	Op Amp 2 Input A
OA2INB	—	6	3	23	25	—	6	3	23	25	I	ANA	Op Amp 2 Input B
OA2INC	—	24	21	11	12	—	24	21	11	12	I	ANA	Op Amp 2 Input C
OA2IND	—	25	22	14	15	—	25	22	14	15	I	ANA	Op Amp 2 Input D
OA2OUT	—	26	23	15	16	—	26	23	15	16	O	ANA	Op Amp 2 Analog Output
OC1A	14	20	17	7	7	11	16	13	43	47	O	—	MCCP1 Output Compare A
OC1B	12	17	14	44	48	12	17	14	44	48	O	—	MCCP1 Output Compare B
OC1C	15	21	18	8	9	15	21	18	8	9	O	—	MCCP1 Output Compare C
OC1D	16	24	21	11	12	16	24	21	11	12	O	—	MCCP1 Output Compare D
OC1E	—	14	11	41	45	—	14	11	41	45	O	—	MCCP1 Output Compare E
OC1F	—	15	12	42	46	—	15	12	42	46	O	—	MCCP1 Output Compare F
OC2A	4	22	19	9	10	4	22	19	9	10	O	—	MCCP2 Output Compare A
OC2B	—	23	20	10	11	—	23	20	10	11	O	—	MCCP2 Output Compare B
OC2C	—	—	—	2	2	—	—	—	2	2	O	—	MCCP2 Output Compare C
OC2D	—	—	—	3	3	—	—	—	3	3	O	—	MCCP2 Output Compare D
OC2E	—	—	—	4	4	—	—	—	4	4	O	—	MCCP2 Output Compare E
OC2F	—	—	—	5	5	—	—	—	5	5	O	—	MCCP2 Output Compare F
OC3A	—	21	18	12	13	—	21	18	12	13	O	—	MCCP3 Output Compare A
OC3B	—	24	21	13	14	—	24	21	13	14	O	—	MCCP3 Output Compare B
OC4	—	18	15	1	1	—	18	15	1	1	O	—	SCCP4 Output Compare
OC5	—	19	16	6	6	—	19	16	6	6	O	—	SCCP5 Output Compare
OCFA	17	25	22	14	15	17	25	22	14	15	I	ST	MCCP/SCCP Output Compare Fault Input A
OCFB	16	24	21	32	35	16	24	21	32	35	I	ST	MCCP/SCCP Output Compare Fault Input B

Legend: ANA = Analog level input/output, ST = Schmitt Trigger input buffer, I^2C™ = I^2C/SMBus input buffer

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4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® devices and improve Data Space memory usage efficiency, the PIC24F instruction set supports both word and byte operations. As a consequence of byte accessibility, all EA calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

Data byte reads will read the complete word, which contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, the data memory and the registers are organized as two parallel, byte-wide entities with shared (word) address decode, but separate write lines. Data byte writes only write to the corresponding side of the array or register, which matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap will be generated. If the error occurred on a read, the instruction underway is completed; if it occurred on a write, the instruction will be executed, but the write will not occur. In either case, a trap is then executed, allowing the system and/or user to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB; the MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow the users to translate 8-bit signed data to 16-bit signed values. Alternatively, for 16-bit unsigned data, users can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

Although most instructions are capable of operating on word or byte data sizes, it should be noted that some instructions operate only on words.

4.2.3 NEAR DATA SPACE

The 8-Kbyte area between 0000h and 1FFFh is referred to as the Near Data Space. Locations in this space are directly addressable via a 13-bit absolute address field within all memory direct instructions. The remainder of the Data Space is addressable indirectly. Additionally, the whole Data Space is addressable using MOV instructions, which support Memory Direct Addressing (MDA) with a 16-bit address field. For PIC24FV16KM204 family devices, the entire implemented data memory lies in Near Data Space (NDS).

4.2.4 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0000h to 07FFh, are primarily occupied with Special Function Registers (SFRs). These are used by the PIC24F core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by that module. Much of the SFR space contains unused addresses; these are read as '0'. The SFR space, where the SFRs are actually implemented, is provided in Table 4-2. Each implemented area indicates a 32-byte region where at least one address is implemented as an SFR. A complete listing of implemented SFRs, including their addresses, is provided in Table 4-3 through Table 4-26.

TABLE 4-2: IMPLEMENTED REGIONS OF SFR DATA SPACE

	SFR Space Address							
	xx00	**xx20**	**xx40**	**xx60**	**xx80**	**xxA0**	**xxC0**	**xxE0**
000h	Core			ICN	Interrupts			—
100h	Timers	CLC	MCCP/SCCP					
200h	MSSP	UART	Op Amp	DAC	—	—	I/O	
300h	A/D/CMTU				—	—	—	—
400h	—	—	—	—	—	—	—	ANSEL
500h	—	—	—	—	—	—	—	—
600h	—	RTCC/Comp	—	Band Gap	—			
700h	—	—	System/ HLVD	NVM/PMD	—	—	—	—

Legend: — = No implemented SFRs in this block.

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4.3.2 DATA ACCESS FROM PROGRAM MEMORY AND DATA EEPROM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program memory without going through Data Space. It also offers a direct method of reading or writing a word of any address within data EEPROM memory. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

Note: The TBLRDH and TBLWTH instructions are not used while accessing data EEPROM memory.

The PC is incremented by 2 for each successive 24-bit program word. This allows program memory addresses to directly map to Data Space addresses. Program memory can thus be regarded as two 16-bit, word-wide address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space which contains the least significant data word, and TBLRDH and TBLWTH access the space which contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

1. TBLRDL (Table Read Low): In Word mode, it maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

   In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when byte select is '1'; the lower byte is selected when it is '0'.

2. TBLRDH (Table Read High): In Word mode, it maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom' byte, will always be '0'.

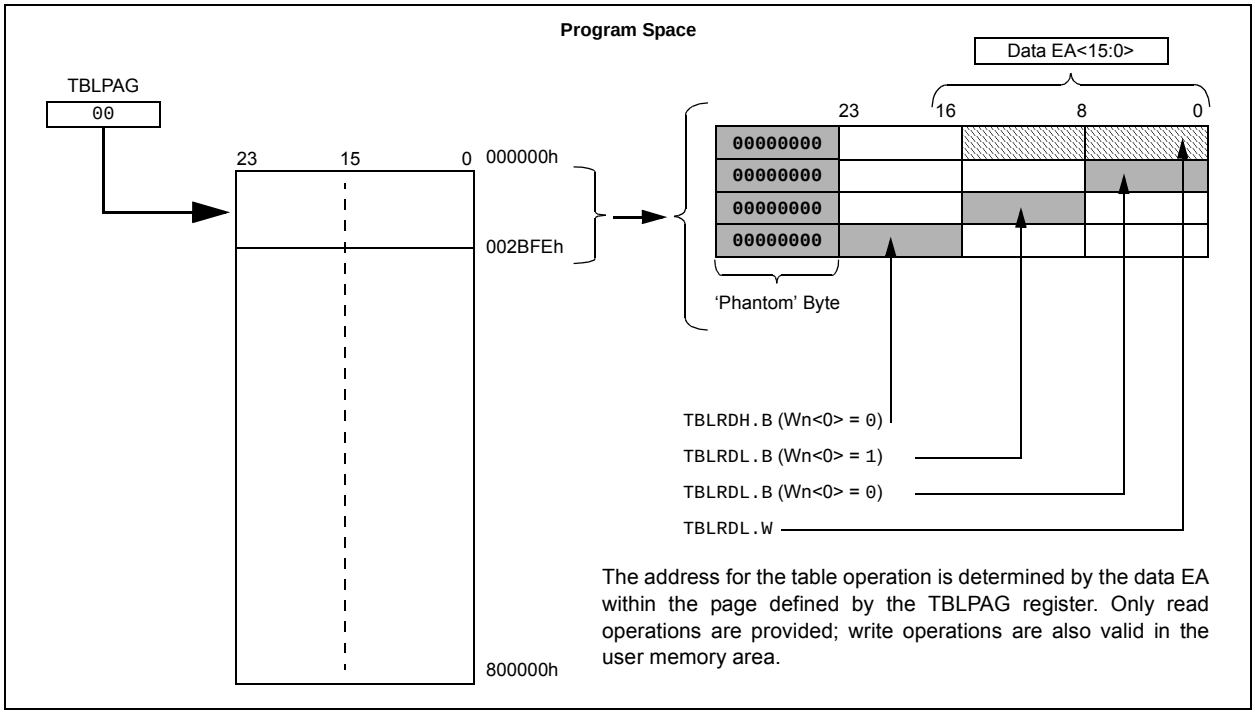
   In Byte mode, it maps the upper or lower byte of the program word to D<7:0> of the data address, as above. Note that the data will always be '0' when the upper 'phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Memory Page Address register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

Note: Only Table Read operations will execute in the configuration memory space, and only then, in implemented areas, such as the Device ID. Table Write operations are not allowed.

FIGURE 4-6: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



The address for the table operation is determined by the data EA within the page defined by the TBLPAG register. Only read operations are provided; write operations are also valid in the user memory area.

4.3.3 READING DATA FROM PROGRAM MEMORY USING PROGRAM SPACE VISIBILITY

The upper 32 Kbytes of Data Space may optionally be mapped into a 16K word page of the program space. This provides transparent access of stored constant data from the Data Space without the need to use special instructions (i.e., TBLRDL/H).

Program space access through the Data Space occurs if the MSb of the Data Space, EA, is '1' and PSV is enabled by setting the PSV bit in the CPU Control (CORCON<2>) register. The location of the program memory space to be mapped into the Data Space is determined by the Program Space Visibility Page Address register (PSVPAG). This 8-bit register defines any one of 256 possible pages of 16K words in program space. In effect, PSVPAG functions as the upper 8 bits of the program memory address, with the 15 bits of the EA functioning as the lower bits.

By incrementing the PC by 2 for each program memory word, the lower 15 bits of Data Space addresses directly map to the lower 15 bits in the corresponding program space addresses.

Data reads from this area add an additional cycle to the instruction being executed, since two program memory fetches are required.

Although each Data Space address, 8000h and higher, maps directly into a corresponding program memory address (see Figure 4-7), only the lower 16 bits of the 24-bit program word are used to contain the data. The upper 8 bits of any program space locations used as data should be programmed with '1111 1111' or '0000 0000' to force a NOP. This prevents possible issues should the area of code ever be accidentally executed.

Note:	PSV access is temporarily disabled during Table Reads/Writes.

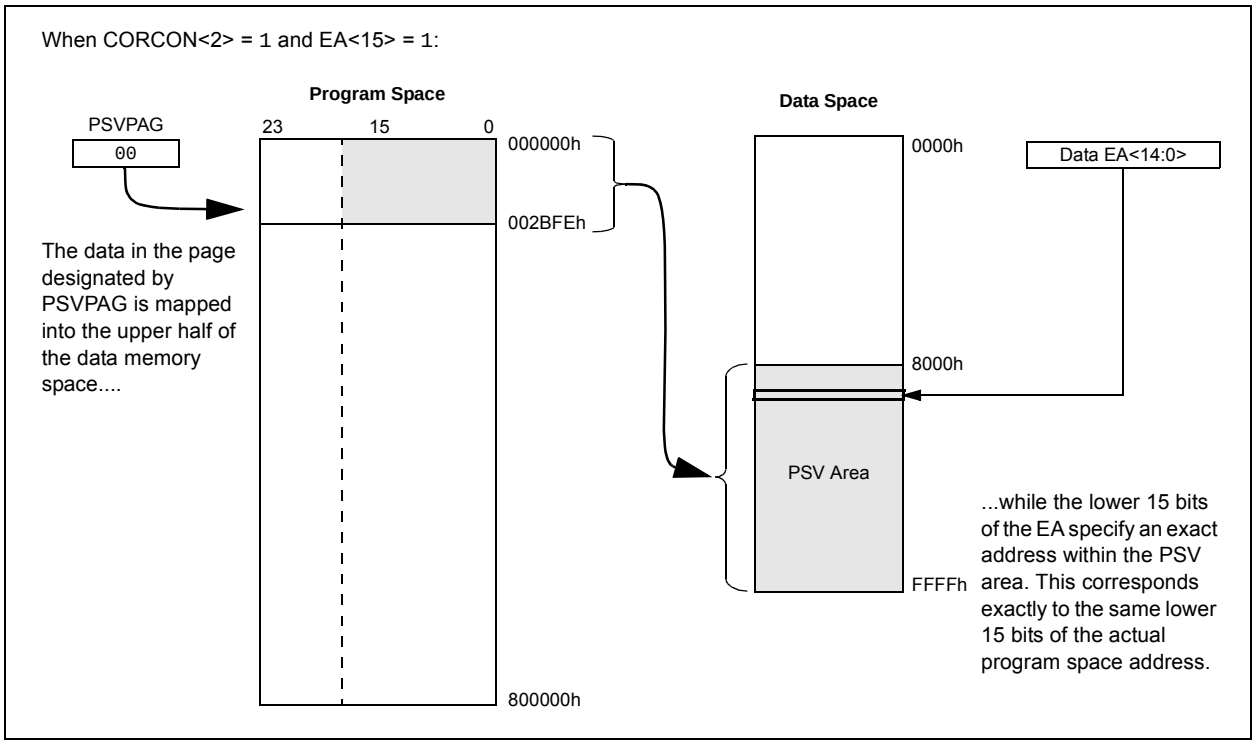
For operations that use PSV and are executed outside a REPEAT loop, the MOV and MOV.D instructions will require one instruction cycle in addition to the specified execution time. All other instructions will require two instruction cycles in addition to the specified execution time.

For operations that use PSV, which are executed inside a REPEAT loop, there will be some instances that require two instruction cycles in addition to the specified execution time of the instruction:

- Execution in the first iteration
- Execution in the last iteration
- Execution prior to exiting the loop due to an interrupt
- Execution upon re-entering the loop after an interrupt is serviced

Any other iteration of the REPEAT loop will allow the instruction accessing data, using PSV, to execute in a single cycle.

FIGURE 4-7: PROGRAM SPACE VISIBILITY OPERATION



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REGISTER 8-1: SR: ALU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R-0, HSC
—	—	—	—	—	—	—	DC(1)
bit 15							bit 8

R/W-0, HSC	R/W-0, HSC	R/W-0, HSC	R-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC
IPL2(2,3)	IPL1(2,3)	IPL0(2,3)	RA(1)	N(1)	OV(1)	Z(1)	C(1)
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)

111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

Note 1: See Register 3-1 for the description of these bits, which are not dedicated to interrupt control functions.

2: The IPL<2:0> bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the Interrupt Priority Level if IPL3 = 1.

3: The IPLx Status bits are read-only when NSTDIS (INTCON1<15>) = 1.

Note: Bit 8 and bits 4 through 0 are described in **Section 3.0 "CPU"**.

10.4 Voltage Regulator-Based Power-Saving Features

The PIC24FV16KM204 family series devices have a voltage regulator that has the ability to alter functionality to provide power savings. The on-chip regulator is made up of two basic modules: the Voltage Regulator (VREG) and the Retention Regulator (RETREG). With the combination of VREG and RETREG, the following power modes are available:

10.4.1 RUN MODE

In Run mode, the main VREG is providing a regulated voltage with enough current to supply a device running at full speed and the device is not in Sleep mode. The RETREG may or may not be running, but is unused.

10.4.2 SLEEP MODE

In Sleep mode, the device is in Sleep and the main VREG is providing a regulated voltage to the core. By default, in Sleep mode, the regulator enters a low-power standby state which consumes reduced quiescent current. The PMSLP bit (RCON<8>) controls the regulator state in Sleep mode. If the PMSLP bit is set, the program Flash memory will stay powered on during Sleep mode and the regulator will stay in its full-power mode.

10.4.3 RETENTION REGULATOR

The Retention Regulator, sometimes referred to as the low-voltage regulator, is designed to provide power to the core at a lower voltage than the standard voltage regulator, while consuming significantly lower quiescent current. Refer to **Section 27.0 "Electrical Characteristics"** for the voltage output range of the RETREG. This regulator is only used in Sleep mode, and has limited output current to maintain the RAM and provide power for limited peripherals, such as the WDT, while the device is in Sleep. It is controlled by the RETCFG Configuration bit (FPOR<2>) and in firmware by the RETEN bit (RCON<12>). RETCFG must be programmed (= 0) and the RETEN bit must be set (= 1) for the Retention Regulator to be enabled.

10.4.4 RETENTION SLEEP MODE

In Retention Sleep mode, the device is in Sleep and all regulated voltage is provided solely by the RETREG, while the main VREG is disabled. Consequently, this mode provides the lowest Sleep power consumption, but has a trade-off of a longer wake-up time. The low-voltage Sleep wake-up time is longer than Sleep mode due to the extra time required to re-enable the VREG and raise the V_{DDCORE} supply rail back to normal regulated levels.

Note:	The PIC24F16KM204 family devices do not have any internal voltage regulation, and therefore, do not support Retention Sleep mode.

TABLE 10-1: VOLTAGE REGULATION CONFIGURATION SETTINGS FOR PIC24FXXXXX FAMILY DEVICES

RETCFG Bit (FPOR<2>)	RETEN Bit (RCON<12>	PMSLP Bit (RCON<8>)	Power Mode During Sleep	Description
0	0	1	Sleep	VREG mode (normal) is unchanged during Sleep. RETREG is unused.
0	0	0	Sleep (Standby)	VREG goes to Low-Power Standby mode during Sleep. RETREG is unused.
0	1	0	Retention Sleep	VREG is off during Sleep. RETREG is enabled and provides Sleep voltage regulation.
1	x	1	Sleep	VREG mode (normal) is unchanged during Sleep. RETREG is disabled at all times.
1	x	0	Sleep (Standby)	VREG goes to Low-Power Standby mode during Sleep. RETREG is disabled at all times.

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REGISTER 14-2: SSPxSTAT: MSSPx STATUS REGISTER (I^2C™ MODE) (CONTINUED)

bit 0 **BF:** Buffer Full Status bit

In Transmit mode:
1 = Transmit is in progress, SSPxBUF is full
0 = Transmit is complete, SSPxBUF is empty

In Receive mode:
1 = SSPxBUF is full (does not include the $\overline{ACK}$ and Stop bits)
0 = SSPxBUF is empty (does not include the $\overline{ACK}$ and Stop bits)

Note 1: This bit is cleared on Reset and when SSPEN is cleared.

2: This bit holds the R/$\overline{W}$ bit information following the last address match. This bit is only valid from the address match to the next Start bit, Stop bit or not $\overline{ACK}$ bit.

3: ORing this bit with SEN, RSEN, PEN, RCEN or ACKEN will indicate if the MSSPx is in Active mode.

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16.2.5 RTCVAL REGISTER MAPPINGS

REGISTER 16-4: YEAR: YEAR VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
YRTEN3	YRTEN2	YRTEN1	YRTEN0	YRONE3	YRONE2	YRONE1	YRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-4 **YRTEN<3:0>:** Binary Coded Decimal Value of Year's Tens Digit bits
Contains a value from 0 to 9.

bit 3-0 **YRONE<3:0>:** Binary Coded Decimal Value of Year's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to the YEAR register is only allowed when RTCWREN = 1.

REGISTER 16-5: MTHDY: MONTH AND DAY VALUE REGISTER(1)

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	DAYTEN1	DAYTEN0	DAYONE3	DAYONE2	DAYONE1	DAYONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **MTHTEN0:** Binary Coded Decimal Value of Month's Tens Digit bit
Contains a value of '0' or '1'.

bit 11-8 **MTHONE<3:0>:** Binary Coded Decimal Value of Month's Ones Digit bits
Contains a value from 0 to 9.

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **DAYTEN<1:0>:** Binary Coded Decimal Value of Day's Tens Digit bits
Contains a value from 0 to 3.

bit 3-0 **DAYONE<3:0>:** Binary Coded Decimal Value of Day's Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

FIGURE 16-2: ALARM MASK SETTINGS

Alarm Mask Setting (AMASK<3:0>)	Day of the Week	Month	Day	Hours	Minutes	Seconds
0000 - Every half second 0001 - Every second						
0010 - Every 10 seconds						s
0011 - Every minute						s s
0100 - Every 10 minutes					m	s s
0101 - Every hour					m m	s s
0110 - Every day				h h	m m	s s
0111 - Every week	d			h h	m m	s s
1000 - Every month			d d	h h	m m	s s
1001 - Every year(1)		m m	d d	h h	m m	s s

Note 1: Annually, except when configured for February 29.

16.5 Power Control

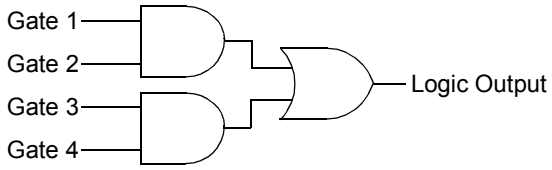
The RTCC includes a power control feature that allows the device to periodically wake-up an external device, wait for the device to be stable before sampling wake-up events from that device and then shut down the external device. This can be done completely autonomously by the RTCC, without the need to wake from the current low-power mode (Sleep, Deep Sleep, etc.).

To enable this feature, the RTCC must be enabled (RTCEN = 1), the PWCEN register bit must be set and the RTCC pin must be driving the PWC control signal (RTCOE = 1 and RTCCLK<1:0> = 11).

The polarity of the PWC control signal may be chosen using the PWCPOL register bit. Active-low or active-high may be used with the appropriate external switch to turn on or off the power to one or more external devices. The active-low setting may also be used in conjunction with an open-drain setting on the RTCC pin. This setting is able to drive the GND pin(s) of the external device directly (with the appropriate external V_{DD} pull-up device), without the need for external switches. Finally, the CHIME bit should be set to enable the PWC periodicity.

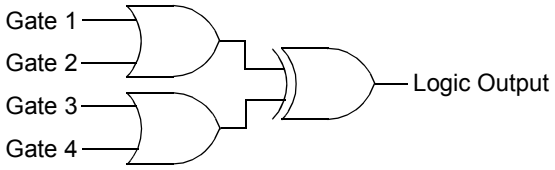
FIGURE 17-2: CLCx LOGIC FUNCTION COMBINATORIAL OPTIONS

AND – OR



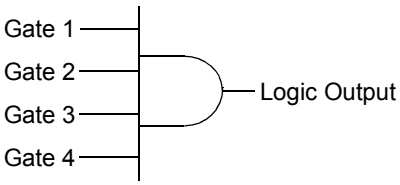
MODE<2:0> = 000

OR – XOR



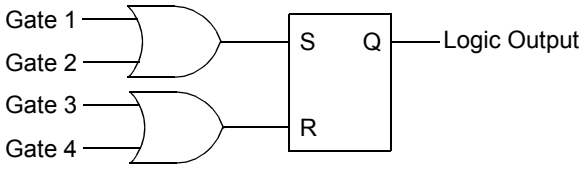
MODE<2:0> = 001

4-Input AND



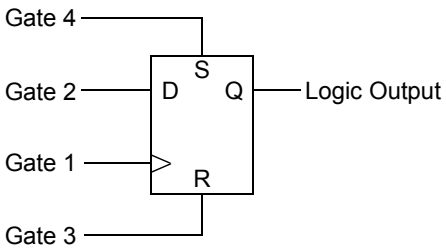
MODE<2:0> = 010

S-R Latch



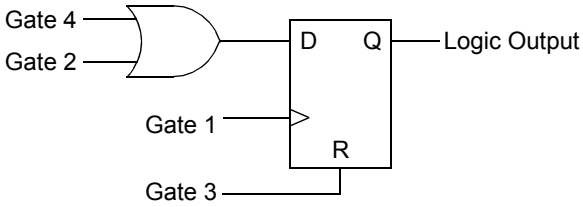
MODE<2:0> = 011

1-Input D Flip-Flop with S and R



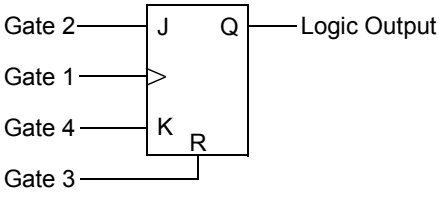
MODE<2:0> = 100

2-Input D Flip-Flop with R



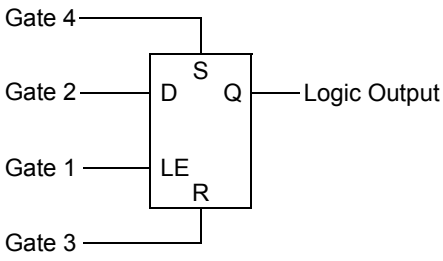
MODE<2:0> = 101

J-K Flip-Flop with R



MODE<2:0> = 110

1-Input Transparent Latch with S and R



MODE<2:0> = 111

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REGISTER 17-4: CLCxGLSL: CLCx GATE LOGIC INPUT SELECT LOW REGISTER (CONTINUED)

bit 3 **G1D2T:** Gate 1 Data Source 2 True Enable bit
1 = The Data Source 2 inverted signal is enabled for Gate 1
0 = The Data Source 2 inverted signal is disabled for Gate 1

bit 2 **G1D2N:** Gate 1 Data Source 2 Negated Enable bit
1 = The Data Source 2 inverted signal is enabled for Gate 1
0 = The Data Source 2 inverted signal is disabled for Gate 1

bit 1 **G1D1T:** Gate 1 Data Source 1 True Enable bit
1 = The Data Source 1 inverted signal is enabled for Gate 1
0 = The Data Source 1 inverted signal is disabled for Gate 1

bit 0 **G1D1N:** Gate 1 Data Source 1 Negated Enable bit
1 = The Data Source 1 inverted signal is enabled for Gate 1
0 = The Data Source 1 inverted signal is disabled for Gate 1

REGISTER 18-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
HLVDEN	—	HLSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
VDIR	BGVST	IRVST	—	HLVDL3	HLVDL2	HLVDL1	HLVDL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **HLVDEN:** High/Low-Voltage Detect Power Enable bit
1 = HLVD is enabled
0 = HLVD is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **HLSIDL:** HLVD Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-8 **Unimplemented:** Read as '0'

bit 7 **VDIR:** Voltage Change Direction Select bit
1 = Event occurs when voltage equals or exceeds trip point (HLVDL<3:0>)
0 = Event occurs when voltage equals or falls below trip point (HLVDL<3:0>)

bit 6 **BGVST:** Band Gap Voltage Stable Flag bit
1 = Indicates that the band gap voltage is stable
0 = Indicates that the band gap voltage is unstable

bit 5 **IRVST:** Internal Reference Voltage Stable Flag bit
1 = Indicates that the internal reference voltage is stable and the High-Voltage Detect logic generates the interrupt flag at the specified voltage range
0 = Indicates that the internal reference voltage is unstable and the High-Voltage Detect logic will not generate the interrupt flag at the specified voltage range, and the HLVD interrupt should not be enabled

bit 4 **Unimplemented:** Read as '0'

bit 3-0 **HLVDL<3:0>:** High/Low-Voltage Detection Limit bits
1111 = External analog input is used (input comes from the HLVDIN pin)
1110 = Trip Point 1(1)
1101 = Trip Point 2(1)
1100 = Trip Point 3(1)
.
.
.
0000 = Trip Point 15(1)

Note 1: For the actual trip point, see **Section 27.0 "Electrical Characteristics"**.

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REGISTER 19-1: AD1CON1: A/DA/D CONTROL REGISTER 1

R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	—	—	MODE12	FORM1	FORM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0, HSC	R/C-0, HSC
SSRC3	SSRC2	SSRC1	SSRC0	—	ASAM	SAMP	DONE
bit 7							bit 0

Legend:	C = Clearable bit	U = Unimplemented bit, read as '0'	
R = Readable bit	W = Writable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** A/D Operating Mode bit
1 = A/D Converter is operating
0 = A/D Converter is off

bit 14 **Unimplemented:** Read as '0'

bit 13 **ADSIDL:** A/D Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **MODE12:** 12-Bit A/D Operation Mode bit
1 = 12-bit A/D operation
0 = 10-bit A/D operation

bit 9-8 **FORM<1:0>:** Data Output Format bits (see the following formats)
11 = Fractional result, signed, left justified
10 = Absolute fractional result, unsigned, left justified
01 = Decimal result, signed, right justified
00 = Absolute decimal result, unsigned, right justified

bit 7-4 **SSRC<3:0>:** Sample Clock Source Select bits
1111 = Reserved
•
•
•
1101 = Reserved
1100 = CLC2 event ends sampling and starts conversion
1011 = SCCP4 Compare Event (CCP4IF) ends sampling and starts conversion
1010 = MCCP3 Compare Event (CCP3IF) ends sampling and starts conversion
1001 = MCCP2 Compare Event (CCP2IF) ends sampling and starts conversion
1000 = CLC1 event ends sampling and starts conversion
0111 = Internal counter ends sampling and starts conversion (auto-convert)
0110 = TMR1 Sleep mode Trigger event ends sampling and starts conversion(1)
0101 = TMR1 event ends sampling and starts conversion
0100 = CTMU event ends sampling and starts conversion
0011 = SCCP5 Compare Event (CCP5IF) ends sampling and starts conversion
0010 = MCCP1 Compare Event (CCP1IF) ends sampling and starts conversion
0001 = INT0 event ends sampling and starts conversion
0000 = Clearing the Sample bit ends sampling and starts conversion

Note 1: This version of the TMR1 Trigger allows A/D conversions to be triggered from TMR1 while the device is operating in Sleep mode. The SSRC<3:0> = 0101 option allows conversions to be triggered in Run or Idle modes only.

TABLE 27-1: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Typ	Max	Unit
Operating Junction Temperature Range	T_J	-40	—	+140	°C
Operating Ambient Temperature Range	T_A	-40	—	+125	°C
Power Dissipation Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$ I/O Pin Power Dissipation: $P_{I/O} = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 27-2: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit	Notes
Package Thermal Resistance, 20-Pin PDIP	θ_{JA}	62.4	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SPDIP	θ_{JA}	60	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SSOP	θ_{JA}	108	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SSOP	θ_{JA}	71	—	°C/W	**1**
Package Thermal Resistance, 20-Pin SOIC	θ_{JA}	75	—	°C/W	**1**
Package Thermal Resistance, 28-Pin SOIC	θ_{JA}	80.2	—	°C/W	**1**
Package Thermal Resistance, 20-Pin QFN	θ_{JA}	43	—	°C/W	**1**
Package Thermal Resistance, 28-Pin QFN	θ_{JA}	32	—	°C/W	**1**
Package Thermal Resistance, 44-Pin QFN	θ_{JA}	29	—	°C/W	**1**
Package Thermal Resistance, 44-Pin TQFP	θ_{JA}	40	—	°C/W	**1**
Package Thermal Resistance, 48-Pin UQFN	θ_{JA}	41	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-$_{JA}$ (θ_{JA}) numbers are achieved by package simulations.

TABLE 27-3: DC CHARACTERISTICS: TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KMXXX)** **2.0V to 5.5V (PIC24FV16KMXXX)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DC10	V_{DD}	**Supply Voltage**	1.8	—	3.6	V	For PIC24F devices
			2.0	—	5.5	V	For PIC24FV devices
DC12	V_{DR}	**RAM Data Retention Voltage(2)**	1.6	—	—	V	For PIC24F devices
			1.8	—	—	V	For PIC24FV devices
DC16	V_{POR}	**V_{DD} Start Voltage** to Ensure Internal Power-on Reset Signal	V_{SS}	—	0.7	V	
DC17	SV_{DD}	**V_{DD} Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	0-3.3V in 0.1s 0-2.5V in 60 ms

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: This is the limit to which V_{DD} can be lowered without losing RAM data.

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TABLE 27-37: A/D MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V (PIC24F16KM204) 2.0V to 5.5V (PIC24FV16KM204) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of: VDD – 0.3 or 1.8	—	Lesser of: VDD + 0.3 or 3.6	V	PIC24FXXKMXXX devices
			Greater of: VDD – 0.3 or 2.0	—	Lesser of: VDD + 0.3 or 5.5	V	PIC24FVXXKMXXX devices
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 1.7	—	AVDD	V	
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 1.7	V	
AD07	VREF	Absolute Reference Voltage	AVSS – 0.3	—	AVDD + 0.3	V	
AD08	IVREF	Reference Voltage Input Current	—	1.25	—	mA	
AD09	ZVREF	Reference Input Impedance	—	10k	—	Ω	
Analog Input							
AD10	VINH-VINL	Full-Scale Input Span	VREFL	—	VREFH	V	**(Note 2)**
AD11	VIN	Absolute Input Voltage	AVSS – 0.3	—	AVDD + 0.3	V	
AD12	VINL	Absolute VINL Input Voltage	AVSS – 0.3	—	AVDD/2	V	
AD17	RIN	Recommended Impedance of Analog Voltage Source	—	—	1k	Ω	12-bit
A/D Accuracy							
AD20b	NR	Resolution	—	12	—	bits	
AD21b	INL	Integral Nonlinearity	—	±1	±9	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5V
AD22b	DNL	Differential Nonlinearity	—	±1	±5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5V
AD23b	GERR	Gain Error	—	±1	±9	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5V
AD24b	EOFF	Offset Error	—	±1	±5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 5V
AD25b		Monotonicity(1)	—	—	—	—	Guaranteed

Note 1: The A/D conversion result never decreases with an increase in the input voltage.

2: Measurements are taken with external VREF+ and VREF- used as the A/D voltage reference.

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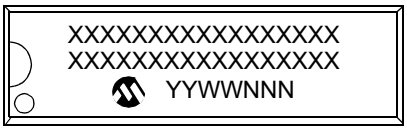
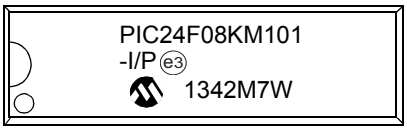
28.0 PACKAGING INFORMATION

28.1 Package Marking Information

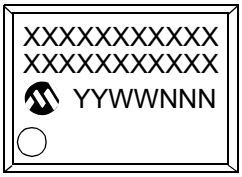
20-Lead PDIP (300 mil)



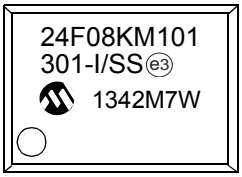
Example



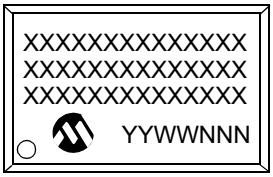
20-Lead SSOP (5.30 mm)



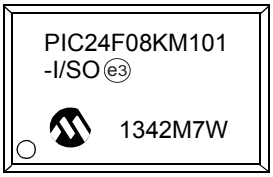
Example



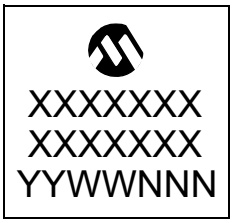
20-Lead SOIC (7.50 mm)



Example



20-Lead QFN



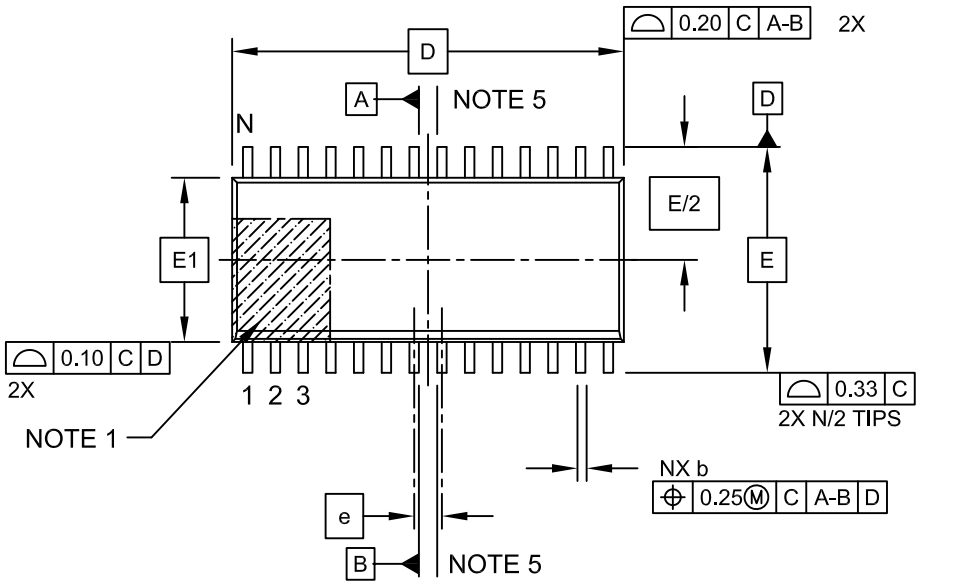
Example

Legend:	XX...X	Product-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

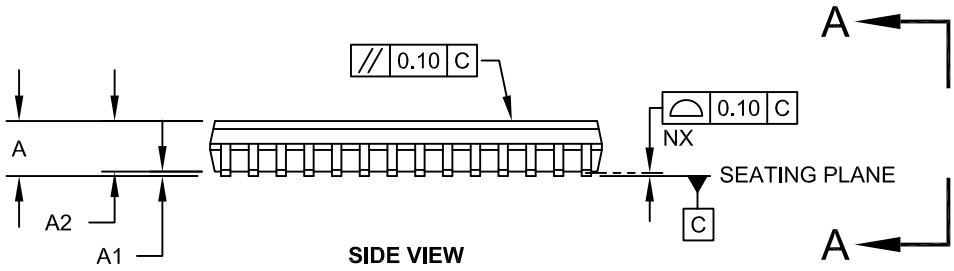
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

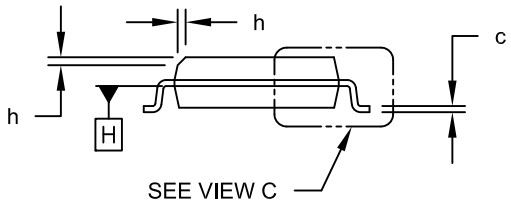
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

Microchip Technology Drawing C04-052C Sheet 1 of 2

APPENDIX A: REVISION HISTORY

Revision A (February 2013)

Original data sheet for the PIC24FV16KM204 family of devices.

Revision B (July 2013)

Updates all references to PGCx and PGDx pin functions throughout the document to PGECx and PGEDx.

Updates **Section 4.0 "Memory Organization"** to change bit 12 in the following registers to reserved ("r" designation):

- CCP1CON1L (Table 4-8)
- CCP2CON1L (Table 4-9)
- CCP3CON1L (Table 4-10)
- CCP4CON1L (Table 4-11)
- CCP5CON1L (Table 4-12)

Updates **Section 13.0 "Capture/Compare/PWM/ Timer Modules (MCCP and SCCP)"**:

- Replaces bit 12 of CCPxCON1L (CCPSLP) and its description with a reserved bit
- Removes references to asynchronous operation in Sleep mode (and in other occurrences throughout the document)
- Modifies **Section 13.1 "Time Base Generator"** to add synchronous operation limitations; adds Table 13-1 to list valid clock options for all operating modes
- Removes the system clock as a time base input option
- Removes external input sources, comparators and CTMU as synchronization sources in Table 13-6; clarifies that other selected sources must be synchronous

Removes the input buffer from the band gap reference input in Figure 20-1.

Adds BUFCON0 register description (Register 20-2) to **Section 20.0 "8-Bit Digital-to-Analog Converter (DAC)"**.

Changes references to internal band gap voltages (V_{BG}, $V_{BG}/2$ and BGBUF0) in **Section 20.0 "8-Bit Digital-to-Analog Converter (DAC)"** and **Section 22.0 "Comparator Module"** to BGBUF1.

Adds minimum V_{DD} conditions for V_{BG} specification in Table 27-15 (Internal Voltage Regulator Specifications).

Other minor typographical corrections throughout the document.